



2827

PATENT
8013-1147

IN THE U.S. PATENT AND TRADEMARK OFFICE

In re application of:

Hirokazu HONDA

Confirmation No. 7187

Serial No. 09/678,609

GROUP 2827

Filed October 4, 2000

Examiner D. Graybill

MULTILAYER INTERCONNECTION BOARD, SEMICONDUCTOR
DEVICE HAVING THE SAME, AND METHOD OF FORMING
THE SAME AS WELL AS METHOD OF MOUNTING THE
SEMICONDUCTOR CHIP ON THE INTERCONNECTION
BOARD

RESPONSE

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

September 2, 2003

Sir:

This replies to the Official Action of July 30, 2003.

Remarks begin on page 2 of this paper.

REMARKS

Responsive to the requirement for election of species, applicant elects metal for the plate material and a solder ball for a preferred species of electrode.

It is believed that claims 1-3, 6-10, 13-21, 27-43, 45-54, and 80-85 are readable on the elected embodiments.

An action on the merits is respectfully requested.

The Commissioner is hereby authorized in this, concurrent, and future replies, to charge payment or credit any overpayment to Deposit Account No. 25-0120 for any additional fees required under 37 C.F.R. § 1.16 or under 37 C.F.R. § 1.17.

Respectfully submitted,

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